

MEMS Manufacturing Solutions



NLD-570EXa for Optical and Biofluidic MEMS Etching

- Stable process and good repeatability
- High selectivity
- Smooth side walls



NE-550EXa Magnetically Enhanced ICP Plasma Etcher

NE Series offers the best RIE process in LED, RF Device, SiC, Noble Metal, III-V Materials and Ferro-Electric Materials

Applications

- Metals
- GaN, Sapphire
- AlGaInP
- GaN/AlGaIn, AlN, SiC
- Ir, Pt/PZT, BST, SBTO

Features

- Temperature control of chamber-wall
- STAR electrode to prevent re-deposition
- Precise depth control (EPM)



ENVIRO-1Xa for MEMS Release and Difficult Strip Applications

The ENVIRO™ Series-1Xa platform can function as a dry plasma, low temperature, polymeric sacrificial layer removal system for MEMS Release applications.

- Wafer sizes 100 – 200 mm
- High throughput platform
- Excellent process control and repeatability



CS-200 Compact Sputtering System for R&D and Production

- Max substrate up to 8"
- Multi-cathode design (max 4)
- Adjustable target to substrate distance (60-180 mm)
- Small footprint
- Easy maintenance
- Deposition up or down
- Single wafer handling (5-wafer cassette option)